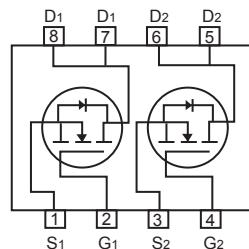
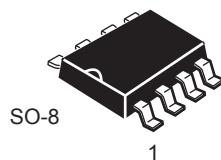


FEATURES

- 60V, 9.0A, $R_{DS(ON)} = 14.5\text{m}\Omega$ @ $V_{GS} = 10\text{V}$.
 $R_{DS(ON)} = 18.0\text{m}\Omega$ @ $V_{GS} = 4.5\text{V}$.
- Super high dense cell design for extremely low $R_{DS(ON)}$.
- High power and current handing capability.
- Lead-free plating ; RoHS compliant.
- Surface mount Package.



ABSOLUTE MAXIMUM RATINGS $T_A = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	9	A
Drain Current-Pulsed ^a	I_{DM}	36	A
Maximum Power Dissipation	P_D	2.0	W
Operating and Store Temperature Range	T_J, T_{Stg}	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol		
Thermal Resistance, Junction-to-Ambient ^b	$R_{\theta JA}$	62.5	$^\circ\text{C/W}$



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Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	60			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 60\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
Gate Body Leakage Current, Forward	I_{GSSF}	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$			100	nA
Gate Body Leakage Current, Reverse	I_{GSSR}	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$			-100	nA
On Characteristics^c						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	1		3	V
Static Drain-Source On-Resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}} = 10\text{V}, I_D = 5.0\text{A}$		11	14.5	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 3.0\text{A}$		12.5	18	$\text{m}\Omega$
Dynamic Characteristics^d						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 25\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		3030		pF
Output Capacitance	C_{oss}			215		pF
Reverse Transfer Capacitance	C_{rss}			140		pF
Switching Characteristics^d						
Turn-On Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}} = 48\text{V}, I_D = 4.5\text{A}, V_{\text{GS}} = 4.5\text{V}, R_{\text{GEN}} = 6\Omega$		33	66	ns
Turn-On Rise Time	t_r			35	70	ns
Turn-Off Delay Time	$t_{\text{d(off)}}$			70	140	ns
Turn-Off Fall Time	t_f			25	50	ns
Total Gate Charge	Q_g	$V_{\text{DS}} = 48\text{V}, I_D = 4.5\text{A}, V_{\text{GS}} = 4.5\text{V}$		35	46	nC
Gate-Source Charge	Q_{gs}			8		nC
Gate-Drain Charge	Q_{gd}			15		nC
Drain-Source Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Current ^b	I_S				1.6	A
Drain-Source Diode Forward Voltage ^c	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_S = 1.6\text{A}$			1.2	V

Notes :

- a.Repetitive Rating : Pulse width limited by maximum junction temperature.
- b.Surface Mounted on FR4 Board, $t \leq 10 \text{ sec.}$
- c.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
- d.Guaranteed by design, not subject to production testing.

CEM

CEM6088L

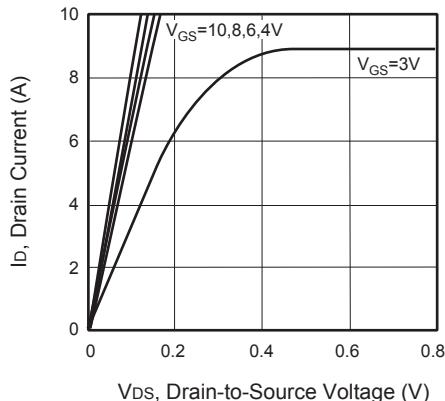


Figure 1. Output Characteristics

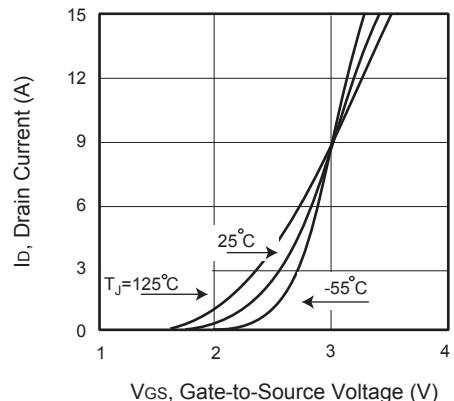


Figure 2. Transfer Characteristics

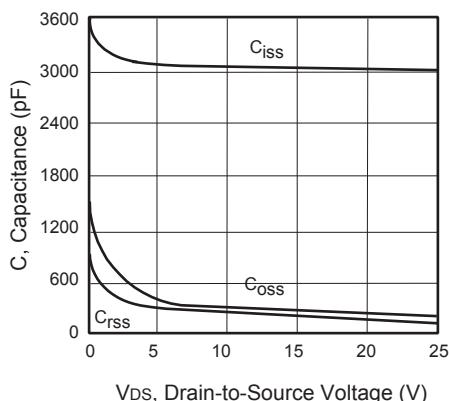


Figure 3. Capacitance

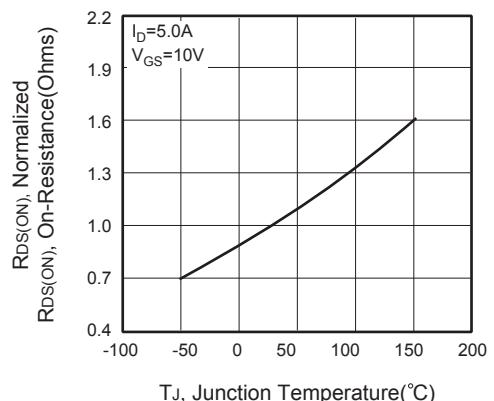


Figure 4. On-Resistance Variation with Temperature

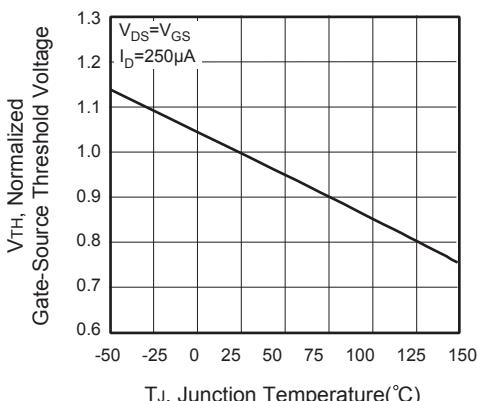


Figure 5. Gate Threshold Variation with Temperature

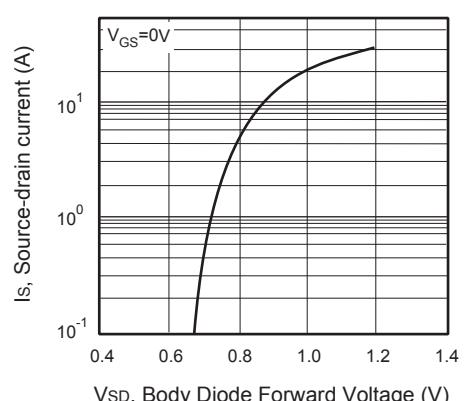
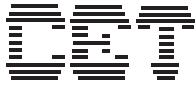


Figure 6. Body Diode Forward Voltage Variation with Source Current



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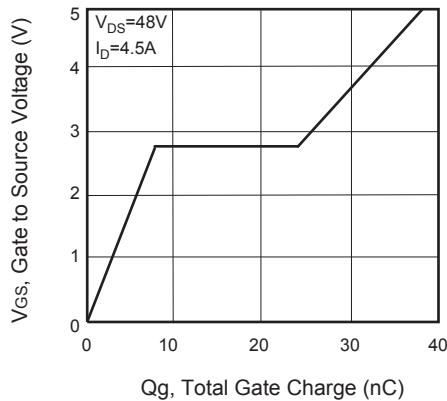


Figure 7. Gate Charge

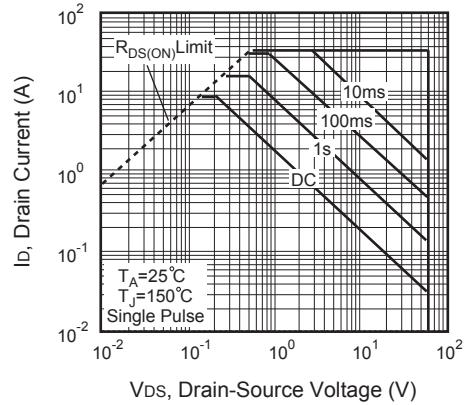


Figure 8. Maximum Safe Operating Area

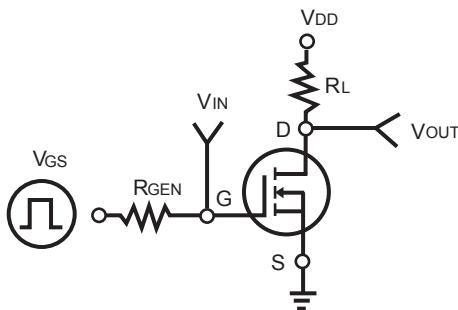


Figure 9. Switching Test Circuit



Figure 10. Switching Waveforms

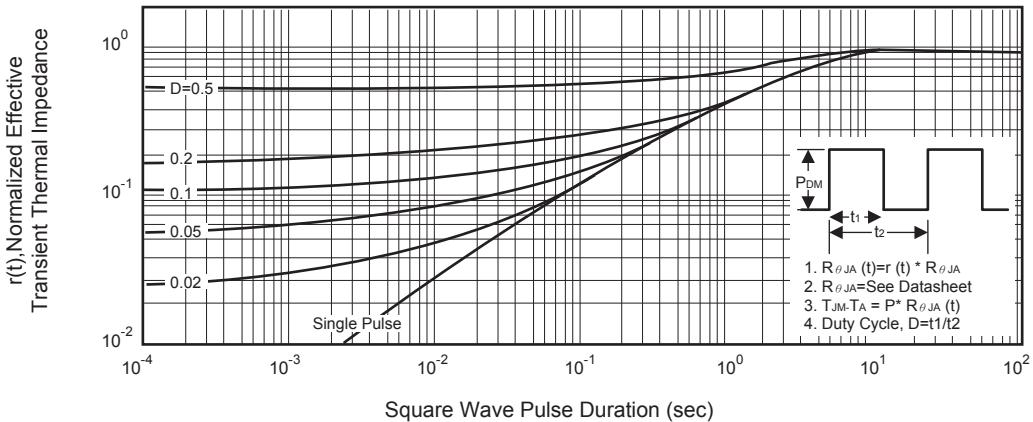


Figure 11. Normalized Thermal Transient Impedance Curve